

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TAKASHI YAMADA	10/21/2015
DAIZO ODA	10/21/2015
RYO OISHI	10/21/2015
TERUO HAIBARA	10/21/2015
TOMOHIRO UNO	10/29/2015
<b>RECEIVING PARTY DATA</b>	
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<b>Street Address:</b>	158-1, OAZA SAYAMAGAHARA, IRUMA-SHI
<b>City:</b>	SAITAMA
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	3580032
<b>Name:</b>	NIPPON STEEL & SUMIKIN MATERIALS CO., LTD.
<b>Street Address:</b>	7-16-3, GINZA, CHUO-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	1040061
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14893833
<b>CORRESPONDENCE DATA</b>	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>ATTORNEY DOCKET NUMBER:</b>	16505-2

<b>NAME OF SUBMITTER:</b>	AARON C. DEDITCH
<b>SIGNATURE:</b>	/Aaron C. Deditch/
<b>DATE SIGNED:</b>	11/24/2015
<b>Total Attachments: 2</b> source=16505-2-Assignment#page1.tif source=16505-2-Assignment#page2.tif	

# U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter "ASSIGNOR") by

(Insert  
ASSIGNEE's  
Name(s)  
Address(es))

1) NIPPON MICROMETAL CORPORATION

158-1, Oaza Sayamagahara, Iruma-shi, Saitama 358-0032, Japan

2) NIPPON STEEL & SUMIKIN MATERIALS CO., LTD.

7-16-3, Ginza, Chuo-ku, Tokyo 104-0061, Japan

(hereinafter "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of  
Invention)

Bonding Wire for Semiconductor Device Use and Method of Production of Same

relating to International Patent Application PCT/JP 2015 / 060035 and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(Insert date  
of execution  
of application,  
if not  
concurrent)

(a) executed on \_\_\_\_\_  
(b) filed on \_\_\_\_\_  
Serial No. \_\_\_\_\_ / \_\_\_\_\_

Assignee's attorney is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

1) <u>Takashi Yamada</u> (SIGNATURE)	Takashi Yamada (TYPE NAME)	October 21, 2015 (DATE)
2) <u>Daizo Oda</u> (SIGNATURE)	Daizo Oda (TYPE NAME)	October 21, 2015 (DATE)
3) <u>Ryo Oishi</u> (SIGNATURE)	Ryo Oishi (TYPE NAME)	October 21, 2015 (DATE)
4) <u>Teruo Haibara</u> (SIGNATURE)	Teruo Haibara (TYPE NAME)	October 21, 2015 (DATE)
5) _____ (SIGNATURE)	Tomohiro Uno (TYPE NAME)	_____ (DATE)
6) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
7) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
8) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)

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(Insert date  
of execution  
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(a) executed on \_\_\_\_\_;  
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Serial No. \_\_\_\_\_/\_\_\_\_\_;

*Assignee's attorney is hereby authorized to insert in (b) the specified data, when known.*

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

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4) _____ (SIGNATURE)	Teruo Haibara _____ (TYPE NAME)	_____ (DATE)
5) <u>Tomohiro Uno</u> (SIGNATURE)	Tomohiro Uno _____ (TYPE NAME)	<u>October 29, 2015</u> (DATE)
6) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
7) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
8) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)